

# Product Change Notification - IIRA-15DIUK933

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**Date:** 28 Apr 2014

**Product Category:** Memory

**Notification subject:** CCB 1397.04 Initial Notice: Qualification of HR-5104 die attach film for 24AA1025, 24AA1026, 24FC1025, 24FC1026, 24LC1025 and 24LC1026 device families in 8L SOIJ package at NSEB (UTL) assembly site.

**Notification text:** **PCN Status:**  
Initial notification

## **Microchip Parts Affected:**

See attachments of affected catalog part numbers (CPN) labeled as...

PCN\_IIRA-15DIUK933\_Affected\_CPN.xls

PCN\_IIRA-15DIUK933\_Affected\_CPN.pdf

## **Description of Change:**

Qualification of HR-5104 die attach film for 24AA1025, 24AA1026, 24FC1025, 24FC1026, 24LC1025 and 24LC1026 device families in the 8L SOIJ package at NSEB (UTL) assembly site.

## **Pre Change:**

HS-231W die attach film

## **Post Change:**

HR-5104 die attach film

## **Impacts to Data Sheet:**

None

**Reason for Change:**

To improve manufacturability

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

July 15, 2014 (date code: 1429)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Markings to Distinguish Revised from Unrevised Devices:**

Traceability code

**Revision History:**

**April 28, 2014:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):** [PCN\\_IIRA-15DIUK933\\_Affected CPN.pdf](#) [PCN\\_IIRA-15DIUK933\\_Qual Plan.pdf](#) [PCN\\_IIRA-15DIUK933\\_Affected CPN.xls](#)

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PCN_IIRA-15DIUK933
CATALOG_PART_NBR
24AA1025-I/SM
24AA1025T-I/SM
24AA1026-I/SM
24AA1026T-I/SM
24FC1025-I/SM
24FC1025T-I/SM
24FC1025T-I/SMC79
24FC1026-I/SM
24FC1026T-I/SM
24LC1025-E/SM
24LC1025-I/SM
24LC1025T-E/SM
24LC1025T-I/SM
24LC1026-E/SM
24LC1026-I/SM
24LC1026T-E/SM
24LC1026T-I/SM



**MICROCHIP**

# **QUALIFICATION PLAN**

**PCN #: IIRA-15DIUK933**

**Date:  
April 9, 2014**

**Qualification of HR-5104 die attach film for 24AA1025,  
24AA1026, 24FC1025, 24FC1026, 24LC1025 and 24LC1026  
device families in the 8L SOIJ package at NSEB (UTL)  
assembly site.**

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**Purpose:** \_\_\_\_\_ Qualification of HR-5104 die attach film for 24AA1025, 24AA1026, 24FC1025, 24FC1026, 24LC1025 and 24LC1026 device families in the 8L SOIJ package at NSEB (UTL) assembly site.

**MP code:** \_\_\_\_\_ 360037C3XB00  
**Part No.:** \_\_\_\_\_ 24AA1025  
**Fab/Node:** \_\_\_\_\_ 160K  
**Die size D5AB2** \_\_\_\_\_ 116.8x112- top and bottom  
\_\_\_\_\_ 92x76 - spacer  
**BD No.:** \_\_\_\_\_ BDE-002614-02  
**CCB No.:** \_\_\_\_\_ 1397.04

**Package code:** \_\_\_\_\_ C3  
**Type:** \_\_\_\_\_ 8L SOIJ  
**Width or Size:** \_\_\_\_\_ 208mils  
**Die thickness:** \_\_\_\_\_ 8mils top/ 8 mil bottom / 8 mils spacer  
**MSL:** \_\_\_\_\_ MSL1

**Lead frame:**  
**Paddle size:** \_\_\_\_\_ 140x160mils  
**Manufacturer:** \_\_\_\_\_ ASM  
**Material:** \_\_\_\_\_ C194  
**Surface:** \_\_\_\_\_ no treatment  
**Paddle plating:** \_\_\_\_\_ bare copper  
**Process:** \_\_\_\_\_ stamped  
**Lead Lock:** \_\_\_\_\_ Yes  
**Part Number:** \_\_\_\_\_ FB0379  
**Strip dimensions:** \_\_\_\_\_ 9.324x2.000

**Wire:**  
**Material:** \_\_\_\_\_ Au

**Die Attach Film:**  
**Part Number:** \_\_\_\_\_ HR-5104  
**Manufacturer:** \_\_\_\_\_ Hitachi  
**Conductive:** \_\_\_\_\_ No

**Mold Compound:**  
**Part Number:** \_\_\_\_\_ G600  
**Manufacturer:** \_\_\_\_\_ Sumitomo

**Lead finish:** \_\_\_\_\_ Matte tin

**Reliability Test plan:** \_\_\_\_\_ STD Package Reliability Test plan on each package.  
Per QC139000

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	3	3	24	0 fails after TC	5	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	3	3	24	0	5	30 bonds from a minimum of 5 devices.
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30	0	5	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	+175°C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25°C and 85°C. 1lot to be tested at 125°C	45	5	3	150	0	10	Must be in progress at time of package release to production, but completion is not required for release to production.
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020D for package type; Electrical test pre and post stress at +25°C. Perform SAM analysis using the standard sample size. MSL1 @ 260°C	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and 85°C. 1lot to be tested at 125°C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Unbiased HAST	+130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs. Electrical test pre and post stress at +25°C.	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at +25°C and 85°C. 1lot to be tested at 125°C 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.